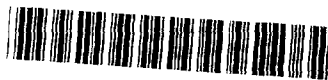


09-21-2001

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U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

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To the Honorable Commissioner of F.

101851203

he attached original documents or copy thereof.

1. Name of conveying party(ies):

Masayuki Hayashi

Hideki Kobayashi

9-17-01

2. Name and address of receiving party(ies):

Name: Dow Corning Toray Silicone Company, Ltd.

Address: 4th Floor AIG Building

1-1-3, Marunouchi, Chiyoda-ku,

Tokyo 100-0005, Japan

SEP 17 2001

City: State/Prov.:

Country: ZIP:

Additional names(s) of conveying party(ies)

☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other

Execution Date: August 8, 2001

Additional name(s) & address(es)

☐ Yes ☒ No

4. Application number(s) or registration numbers(s):

If this document is being filed together with a new application, the execution date of the application is:

Patent Application No.

Filing date

B. Patent No.(s)

09/891,713

June 26, 2001

Additional numbers

☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Patricia M. Scaduto

Registration No.

Address:



00137

PATENT TRADEMARK OFFICE

City: State/Prov.:

Country: USA

ZIP:

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ 40.00

☐ Enclosed - Any excess or insufficiency should be credited or debited to deposit account☒ Authorized to be charged to deposit account

8. Deposit account number:

04-1520

09/20/2001 DBYRME 00000028 041520 09891713

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09/20/2001 09/20/2001

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Patricia M. Scaduto

Patricia M. Scaduto

9-05-01

Name of Person Signing

Signature

3

Date

Total number of pages including cover sheet, attachments, and

ASSIGNMENT

WHEREAS We, Masayuki Hayashi and Hideki Kobayashi have invented certain new and useful improvements in

HIGH ENERGY RADIATION-CURABLE COMPOSITION AND RESIN MOLDING

for which application for United States Letters Patent has been executed by us on this 8th day of August, 2001; and,

WHEREAS, DOW CORNING TORAY SILICONE COMPANY, LTD., 4th Floor, AIG Building, 1-1-3, Marunouchi, Chiyoda-ku, Tokyo 100-0005, JAPAN, is desirous of acquiring the said invention and said application and any and all Letters Patent that may be obtained therefor or thereupon, and all reissues and extensions thereof;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that for and in consideration of the sum of 250 Yen, and other good and valuable considerations, to us in hand paid by the said DOW CORNING TORAY SILICONE COMPANY, LIMITED, the receipt of which is hereby acknowledged, we have sold, assigned, transferred and set over and by these presents do sell, assign, transfer and set over unto the said DOW CORNING TORAY SILICONE COMPANY, LTD., its successors, and assigns, the full and exclusive right, title and interest in and to said invention and said application for Letters Patent of the United States therefor, and in and to any Divisions and Continuations thereof and in and to any and all United States Letters Patent and reissues and extensions thereof that may be issued for the said invention, to have and to hold for its own use and behoof and the use and behoof of its successors and assigns as fully and entirely as the same might be enjoyed by us if this sale and assignment had not been made; and

HEREBY AUTHORIZE and request the Commissioner of Patents and Trademarks to issue the said Letters Patent and any reissues and extensions thereof to the said DOW CORNING TORAY SILICONE COMPANY, LTD. as assigns of the entire right, title and interest in and to the said invention and said application and Letters Patent issued therefor or thereupon; and

HEREBY AGREE to execute all instruments and documents within our power which may be necessary for the carrying out of this assignment in full; and to execute any divisional or continuing application or applications which may be necessary or proper to obtain full protection on the invention hereby assigned; and to execute any and all supplemental oaths and preliminary statements should the same be proper and necessary in the prosecution of the aforesaid applications; and

HEREBY FURTHER ASSIGN unto the said DOW CORNING TORAY SILICONE COMPANY, LIMITED, its successors, and assigns, the whole right, title and interest in and to the invention disclosed in the said application throughout all countries foreign to the United States, and do hereby ratify any acts of the said DOW CORNING TORAY SILICONE COMPANY, LIMITED, its successors and assigns, in applying for patents therefor in its own name in countries where such procedure is proper and do agree to execute applications for said invention in the several countries where it is necessary that the same be executed by the inventors, and to execute assignments of such applications and the patents to be obtained therefor to the said DOW CORNING TORAY SILICONE CO., LTD., its successors and assigns.

IN WITNESS WHEREOF I have hereunto set my hand

Masayuki Hayashi
Masayuki Hayashi

August 8, 2001
Date

This is to certify that Masayuki Hayashi has signed this document in my presence this 8th day of August, 2001, Japan.

Hikari Haga
Signature of Witness
Hikari Haga

IN WITNESS WHEREOF I have hereunto set my hand

Hideki Kobayashi
Hideki Kobayashi

August 8, 2001
Date

This is to certify that Hideki Kobayashi signed this document in my presence this 8th day of August, 2001, Japan.

Hikari Haga
Signature of Witness
Hikari Haga